

Performance characterisation of ALPIDE after 2.7 Mrad proton irradiation at NPI

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Motivation for the ALICE upgrade

Increase of delivered luminosity of Pb-Pb (100× w.r.t. current state) [1]

Physics Goal → high-precision measurements of QGP properties

- Open HF hadrons, quarkonia down to zero p_T
 Thermalization, hadronization, recombination,
 temperature evolution of the QGP
- Vector mesons and low-mass di-leptons
 Chiral symmetry restoration, thermal radiation
 from the QGP
- High-precision measurements of the light
 (anti-)nuclei and hypernuclei
 nucleosynthesis, exotics

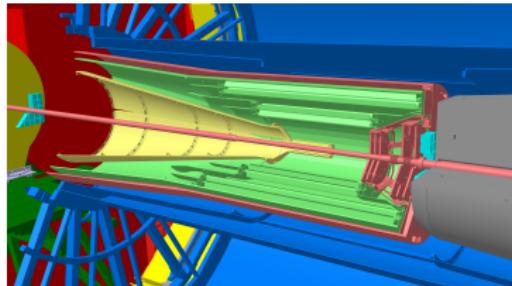
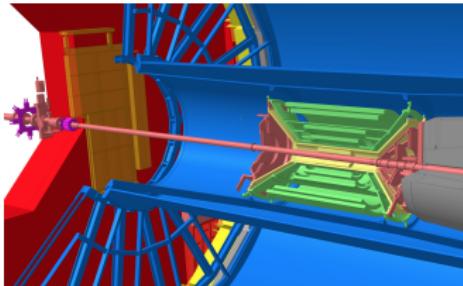


ALICE Upgrade LoI
Mar 2013

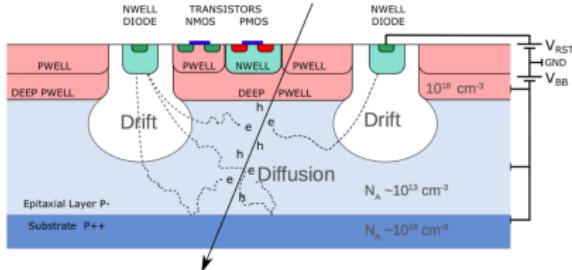
[1] K. Aamodt et. al.(ALICE collaboration), *Phys. Rev. Lett.* **105** 252301(2010)

ALICE Inner Tracking System Upgrade

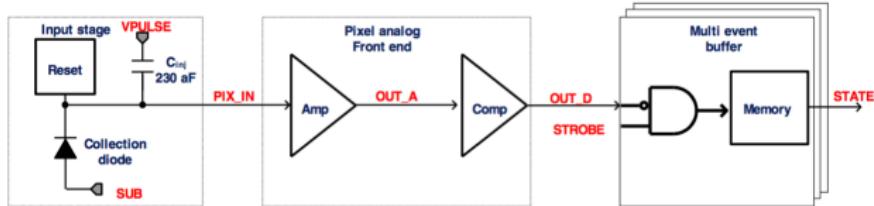
- Improve impact parameter resolution by factor of $\sim 3(5)$
 - ▶ Get closer to IP (position of first layer): $39 \text{ mm} \rightarrow 23 \text{ mm}$
 - ▶ Reduce pixel size $50 \mu\text{m} \times 425 \mu\text{m} \rightarrow 29 \mu\text{m} \times 27 \mu\text{m}$
 - ▶ Reduce material budget: $1.14\% \rightarrow 0.3\% X_0$ per layer in IB
- Improve tracking efficiency and p_T resolution at low p_T
 - ▶ 6 layers \rightarrow 7 layers
 - ▶ Silicon pixel, drift, strip \rightarrow only pixels (ALPIDE)
- Fast readout
 - ▶ readout Pb–Pb interactions at $> 100 \text{ kHz}$
- Fast insertion/removal for yearly maintenance



ALPIDE Sensor

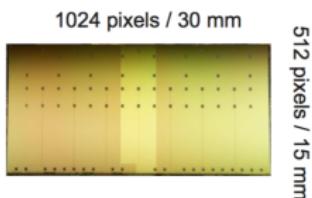


- Monolithic Active Pixel Sensor (MAPS) 180 nm CMOS Imaging by Tower Jazz, each ALPIDE pixel contains sensitive volume, amplification and discrimination
- High resistivity $> 1\text{k}\Omega \text{ cm}$ p-type epitaxial layer 25 μm thick on p-type substrate; deep p-well shielding PMOS transistors
- Small n-well diode 2 μm diameter, much smaller than pixel
- Threshold is regulated by global DACs: V_{CASN} , I_{THR}



ALPIDE requirements and performance

	Inner Barrel	Outer Barrel	ALPIDE performance
Thickness [µm]	50	100	OK
Spatial resolution [µm]	5	10	~ 5
Chip dimension [mm]	15×30	15×30	OK
Power density [mW/cm ²]	< 300	< 100	< 40
Event-time resolution [µs]	< 30	< 30	~ 2
Detection efficiency [%]	> 99	> 99	OK
Fake-hit rate [event ⁻¹ pixel ⁻¹]	< 10^{-6}	< 10^{-6}	< 10^{-10}



Radiation load for the Inner Barrel:
 TID 270 krad (Total Ionizing Dose)
 NIEL $1.3 \times 10^{12} \text{ 1MeV n}_{\text{eq}} \cdot \text{cm}^{-2}$
 (Non-Ionizing Energy Loss)
 Chip is tested with a safety factor of 10

Radiation Hardness Tests at NPI

- Cyclotron provides protons with $E = 35 \text{ MeV}$
- Beam current $I \approx 50 \text{ pA}$
- On-line monitoring using ionization chamber 30100 PTW Freiburg
- TID and NIEL are calculated using stopping power of material (S) and fluence (F)



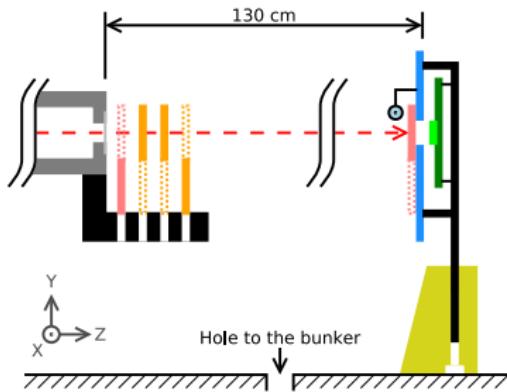
$$\text{TID [krad]} = 1.602 \times 10^{-8} \times S [\text{MeV} \cdot \text{cm}^2 \cdot \text{mg}^{-1}] \times F [\text{cm}^{-2}]$$

$$\text{NIEL [1 MeV n}_{\text{eq}} \text{ cm}^{-2}\text{]} = 2.346 \times F [\text{cm}^{-2}]$$

[2] F. Křížek, ... V. Raskina, ... , Nuclear Inst. and Methods in Physics Research, A 894 (2018) 87–95.

[3] Non Ionizing Energy Loss (NIEL), <https://rd50.web.cern.ch/rd50/NIEL/default.html>

Setup

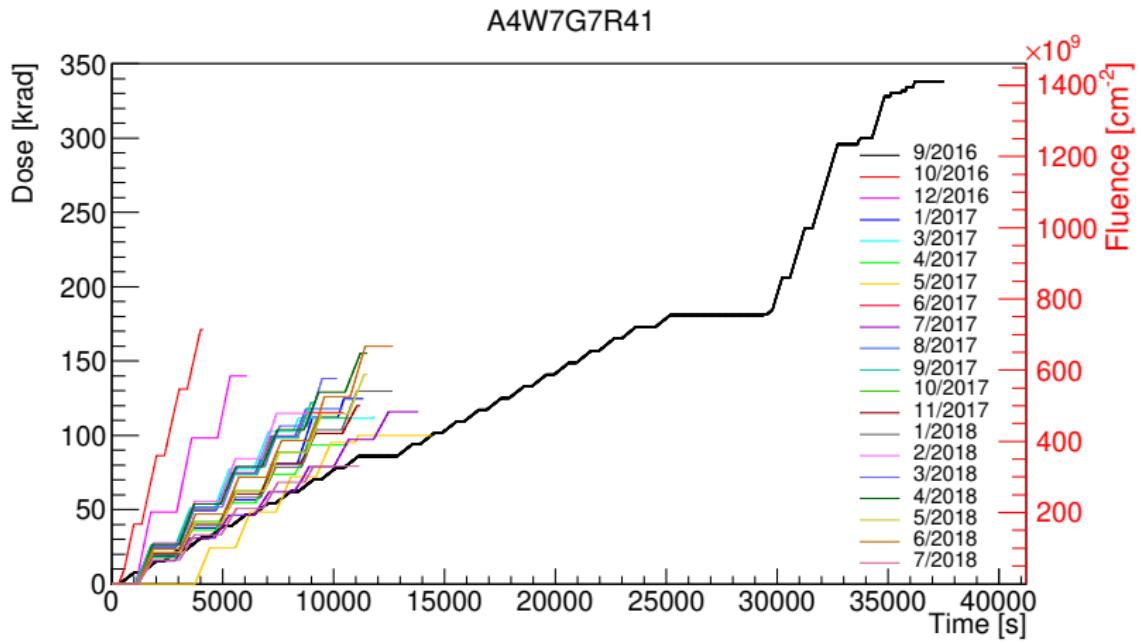


- Energy degrader plates (0.5 - 2 mm Al)
- Beam stop plates (8 mm Al)
- Shielding (8 mm Al)
- Ionization chamber
- Irradiated sample (FPGA chip)
- Shielded part of target (circuit board)
- X-Y positioning mechanism (MCL)
- Beam pipe and its exit window
- Proton beam



Irradiation of the chip

- Threshold and DAC scans are made when beam is stopped
- Each time chip receives TID ≈ 100 krad ($\approx 1/3$ of the total dose in Run3)

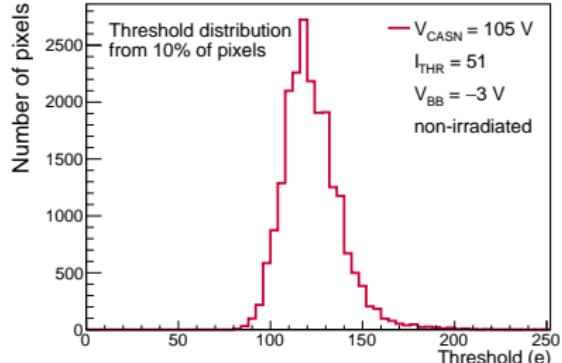
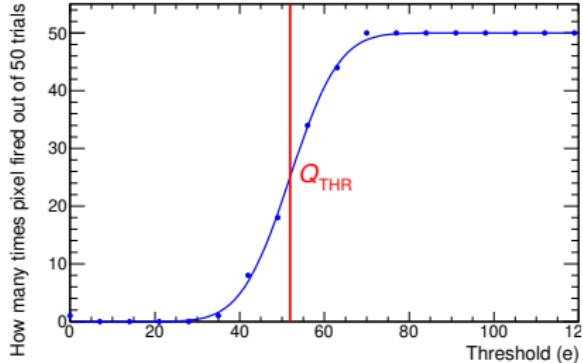


Charge threshold and temporal noise measurement

Firing probability of a pixel is tested by inducing a given charge 50 times on the analog part of pixel. The firing probability is described by S-function:

$$S(Q) = \frac{1}{2} \left(50 + 50 \times \text{erf} \left(\frac{Q - Q_{\text{THR}}}{\sqrt{2}\sigma} \right) \right),$$

Q - induced charge, Q_{THR} - threshold, σ - noise.

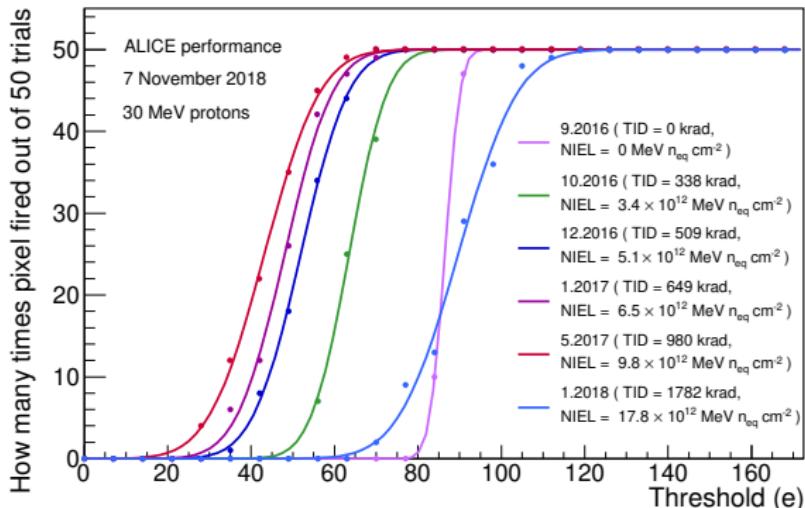


S curves for different time periods for chosen pixel

Shift of the S curve to the **left/right** corresponds to **decrease/increase** of threshold.

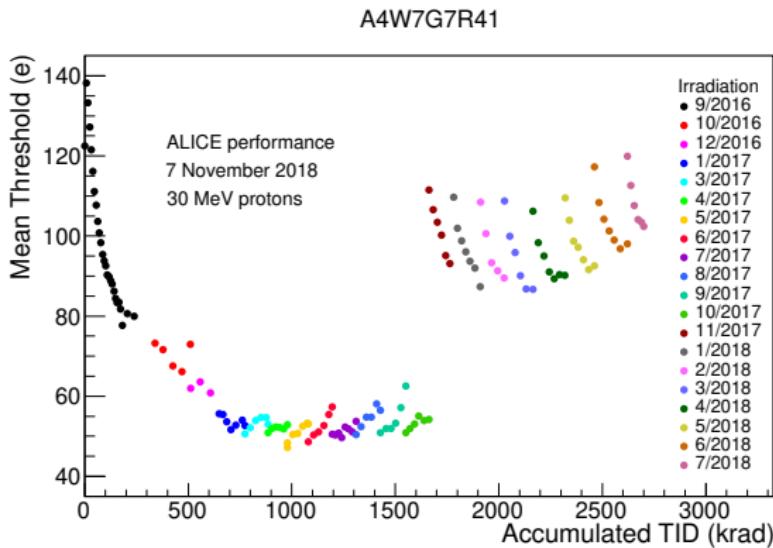
Broadening of the transition region corresponds to increase of noise.

A4W7G7R41 pixel 252,252



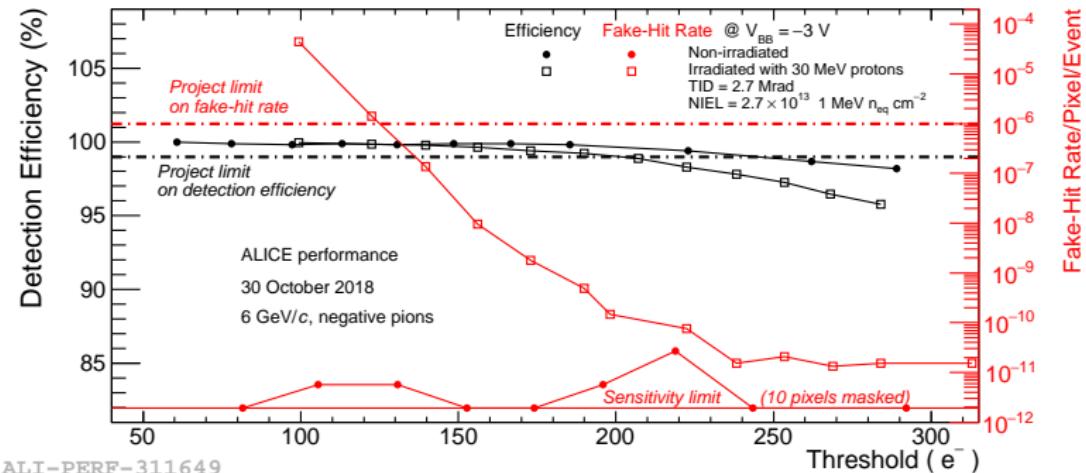
Mean threshold vs. TID

- Average threshold over 10% of 0.5 M pixels
- With initial settings of I_{THR} and $V_{CASN} \rightarrow$ threshold decreased
- Since Nov 2017, running with decreased V_{CASN} settings \rightarrow since then we observe annealing



Fake-Hit Rate and Efficiency

- Irradiated chip obtained TID of 2700 krad and NIEL of $2.7 \times 10^{13} \text{ 1 MeV n}_{\text{eq}} \text{cm}^{-2}$
- ALPIDE chip was tested at CERN PS with 6 GeV pion beam
- Limit on detection efficiency $> 99\%$
- Limit on fake - hit rate $< 10^{-6} \text{event}^{-1} \text{pixel}^{-1}$



ALI-PERF-311649

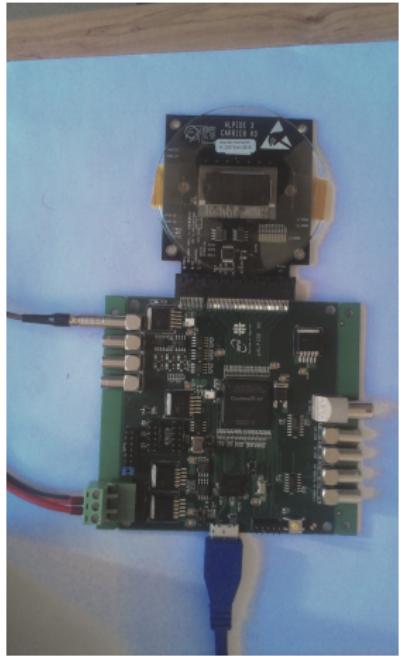
Summary

- ALICE will upgrade its Inner Tracking System (ITS) detector in LS2
- The radiation hardness tests of the ALPIDE sensors were done at U-120M cyclotron with 30 MeV proton beam
- ALPIDE chip which obtained TID of 2700 krad and NIEL of 2.7×10^{13} 1 MeV n_{eq}cm⁻² meets the requirements for the new ITS

Backup



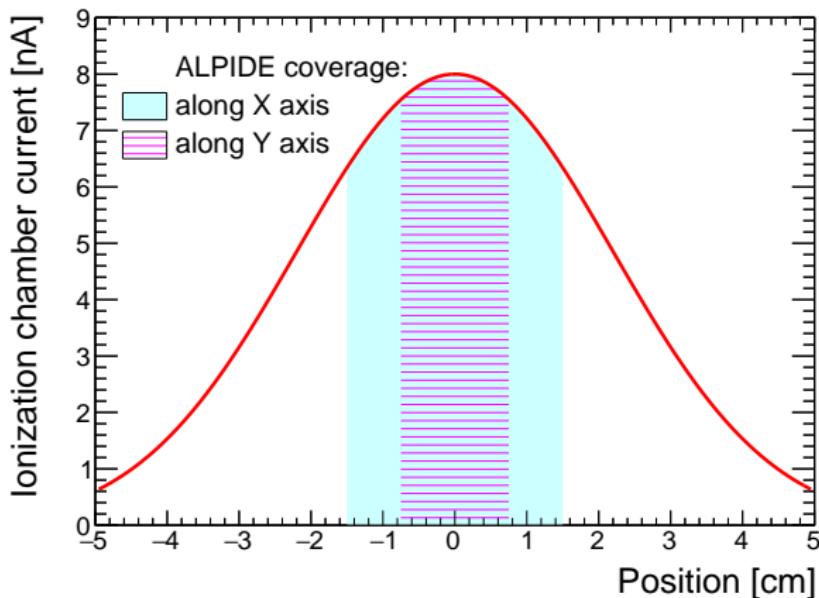
Ionization chamber and ALPIDE



DAQ board (read-out) and
Carrier card with ALPIDE chip

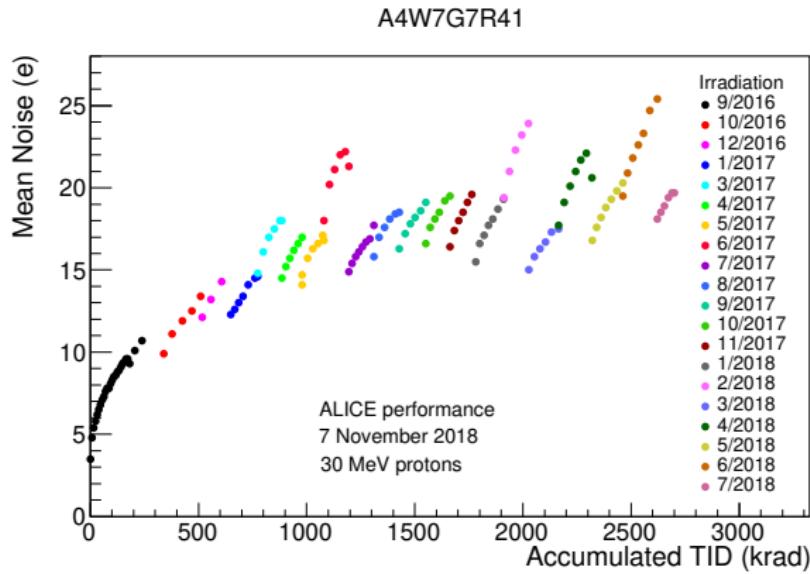
Proton beam profile

- Beam profile is a 2D symmetric gaussian
- 0.56 mm thick Al degrader plate is used to increase its width to $\sigma \approx 22$ mm



Mean noise vs. TID

- Average noise over 10 % pixels out of 0.5 M
- Noise is continuously increasing with TID
- Annealing is present but small



Resolution and Cluster size of irradiated and non-irradiated chip

The required spatial resolution is $\sim 5 \mu\text{m}$

